

End of Life Plan

Kodak Scan Station 700 Series

Network Scanners



Compositional Analysis

This compositional analysis applies to model(s): Scan Station 700 Series Network Scanners. The following table identifies the location of materials that need special treatment by recyclers.

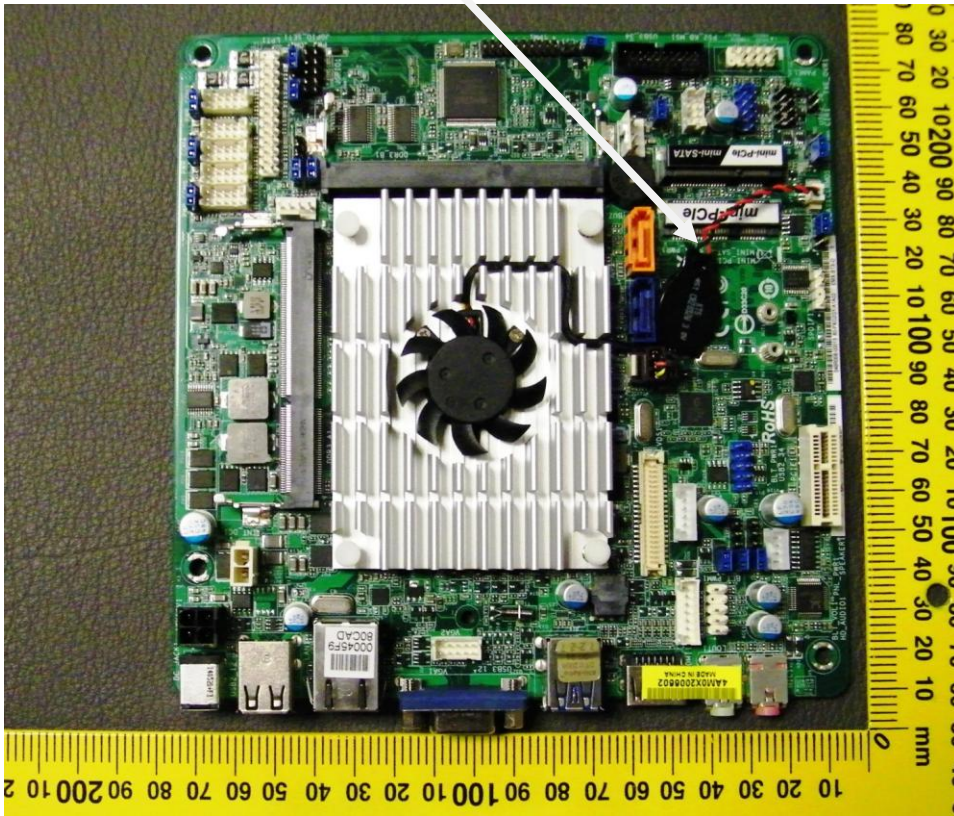
Material of concern	Present in part?	Describe Specific Component and/or location
External Battery	no	
Internal Battery	yes	A Lithium button cell CR2032 Battery is located on the Mother board inside the card cage. See page 3
Asbestos	no	
Backlighting lamps	no	
Beryllium Oxide	no	
Other forms of Beryllium	no	
Cadmium	no	
Capacitors with PCB's	no	
Capacitors with substances of concern and height > 25 mm, diameter > 25 mm or proportionately similar volume	no	
Chromium VI	no	
Gas discharge lamps	no	
Lead (In accordance with EU RoHS exemptions)	yes	Ac Adapter, data and power cable, memory module on motherboard
Liquid Crystal Displays with a surface area > 100cm ²	yes	Located on the top side of the scanner.
Mercury	no	
Plastic containing brominated flame retardants	no	
Printed Circuit Boards >10 square centimeters	yes	<ul style="list-style-type: none"> • Upper and lower scan module PCB located upon removing front and back cover. Pages 4 - 5 • LCD Display PCB Page 6 • Motherboard and power distribution board located inside Electronics box Pages 7 - 9 • Scan Module Control PCB – Pages 10 - 11
PVC/PVDC	yes	Wire insulation, USB and power cable insulation -connectors - plugs
Radio-active substances	no	

Refractory ceramic fibers	no	
Compartments / units / parts under pressure	no	
Compartments / units / contain liquids	no	
Compartments / units / contain gasses	no	
Compartments / units / contain "Hidden" mechanical springs or other equivalent parts	no	
Lasers	no	

Battery on Mother Board

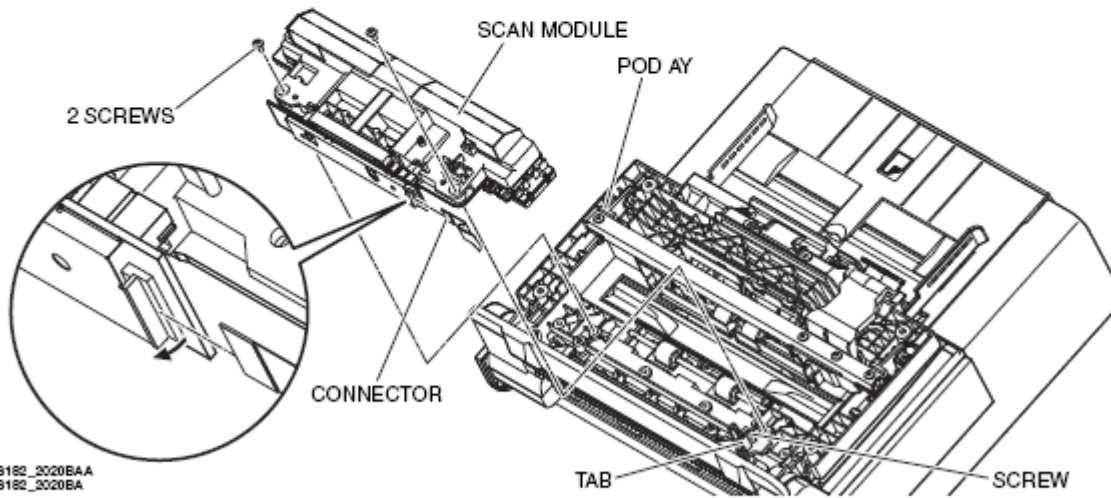
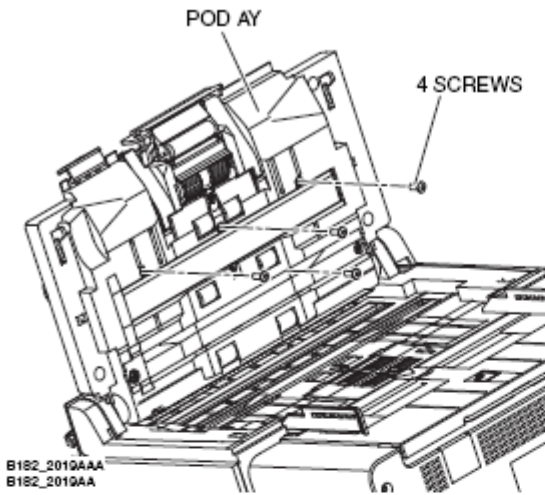


or Battery on Mother Board



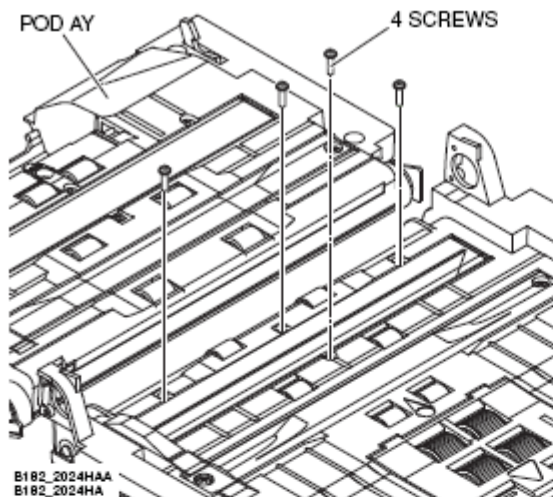
Upper Scan Module Printed Circuit Board removal

- [1] Open the POD AY.
- [2] Remove the 4 T-10 SCREWS.

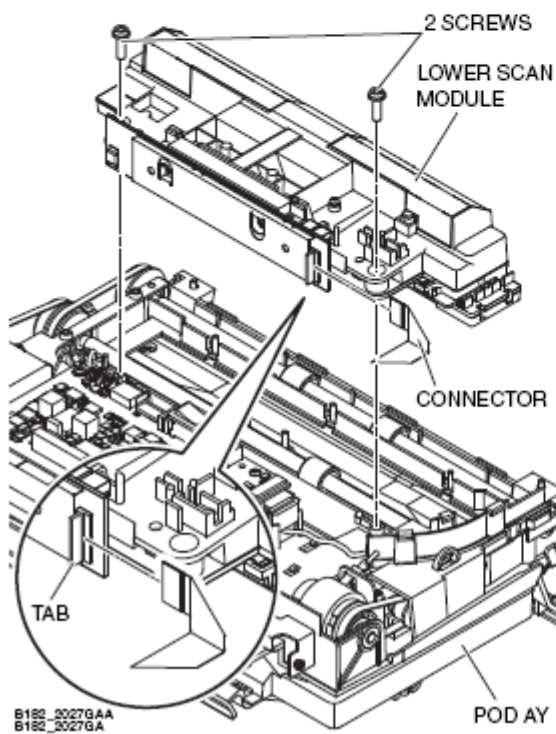


- [3] Close the POD AY
- [4] Remove the 2 T-20 SCREWS.
- [5] Loosen the T-20 SCREW.
- [6] Rotate the black TAB up 90 degrees.
- [7] Disconnect the CONNECTOR.
- [8] Remove the SCAN MODULE.

Lower Scan Module Printed Circuit Board removal

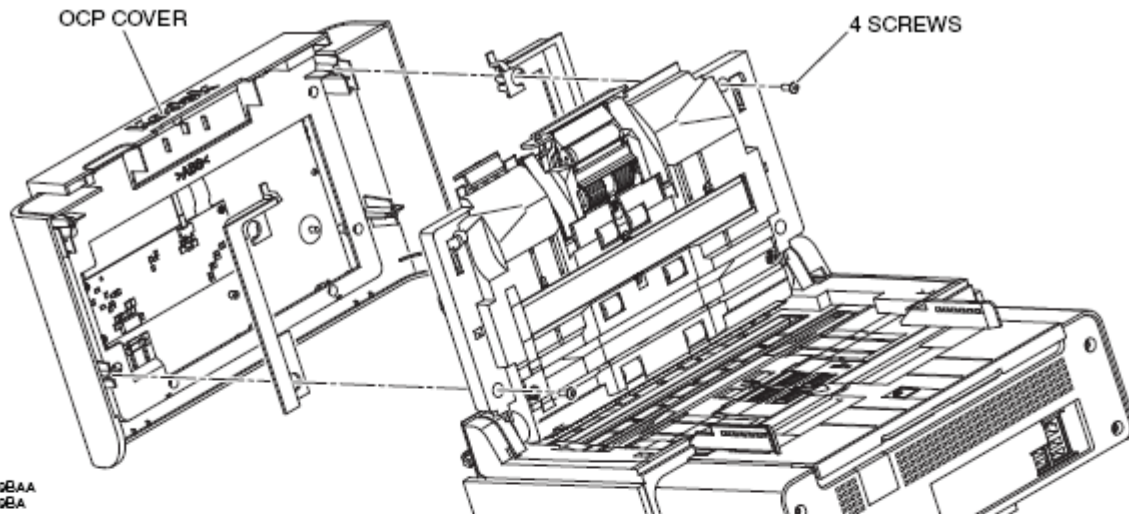


- [1] Open the POD AY.
- [2] Remove the 4 T-10 SCREWS.

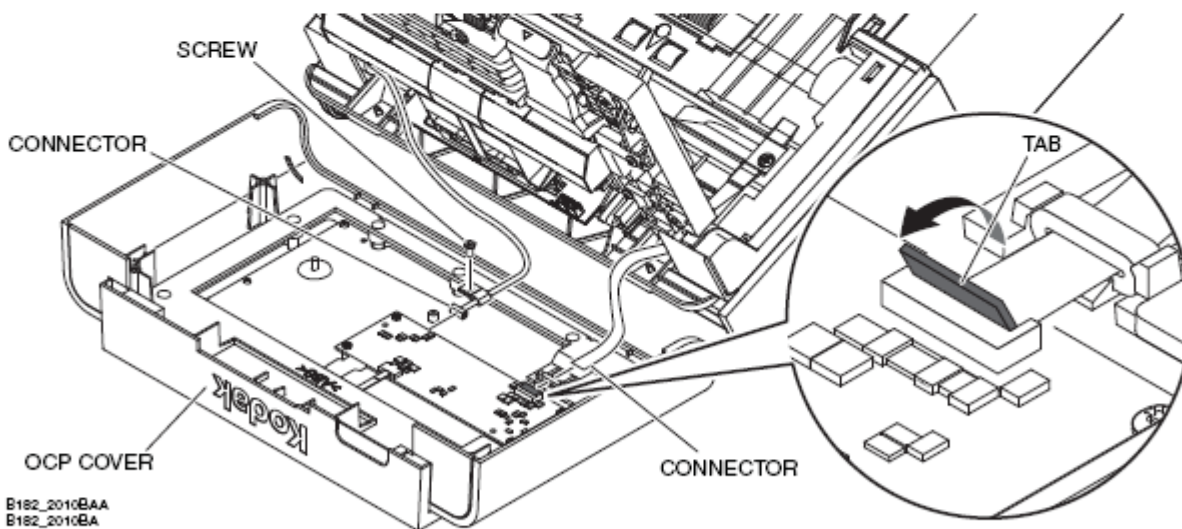


- [3] Close the POD AY.
- [4] Remove the 2 T-20 SCREWS.
- [5] Rotate the black TAB up 90 degrees.
- [6] Disconnect the CONNECTOR.
- [7] Remove the LOWER SCAN MODULE.

LCD Display Printed Circuit Board removal



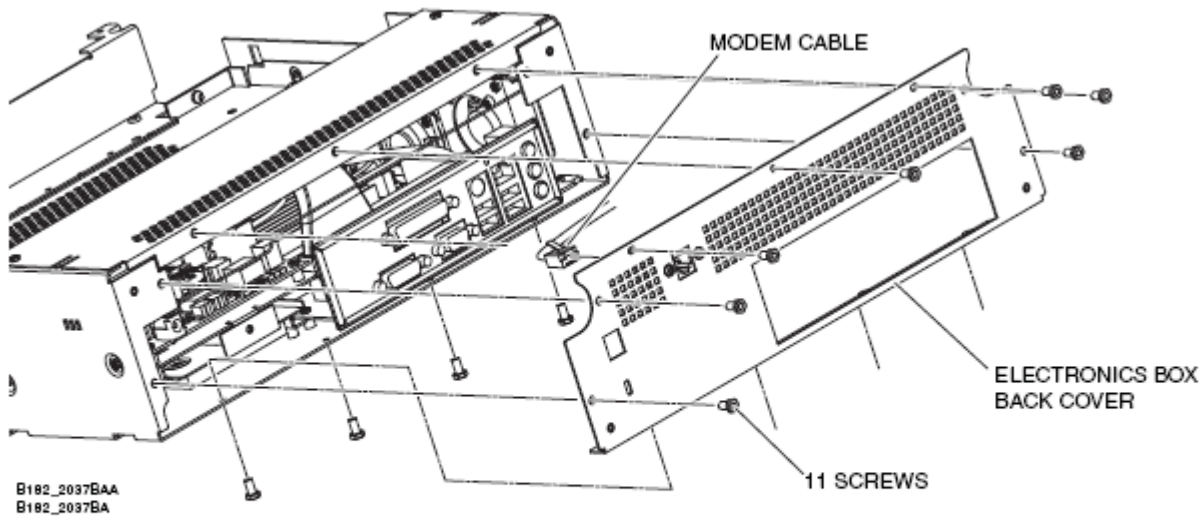
- [4] Remove the 4 T-20 SCREWS. When you remove the last SCREW, hold the OCP COVER to prevent it from falling.
- [5] Place the OCP COVER onto a flat surface.



- [6] Rotate the black TAB up 90 degrees.
- [7] Disconnect the CONNECTOR.
- [8] Loosen the SCREW.
- [9] Disconnect the CONNECTOR.
- [10] Remove the OCP COVER.

Mother board and Power Distribution Printed Circuit Board removal.

Remove Electronic covers as instructed



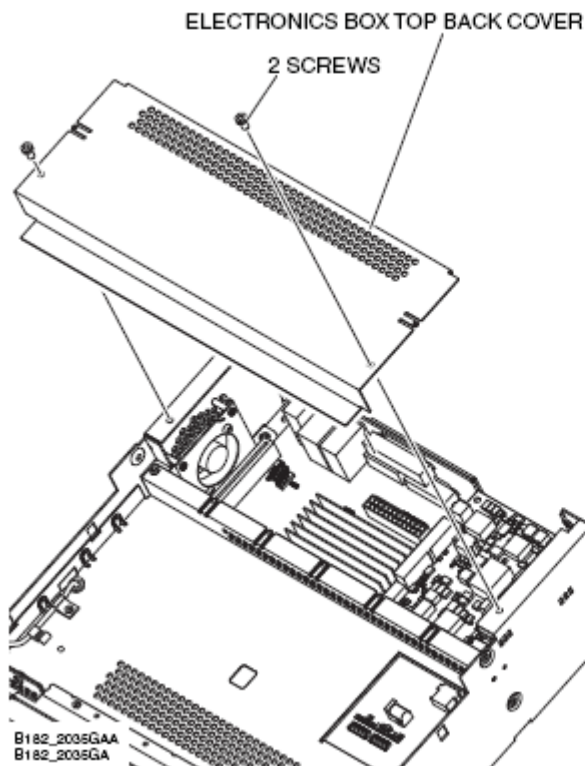
[1] Remove:

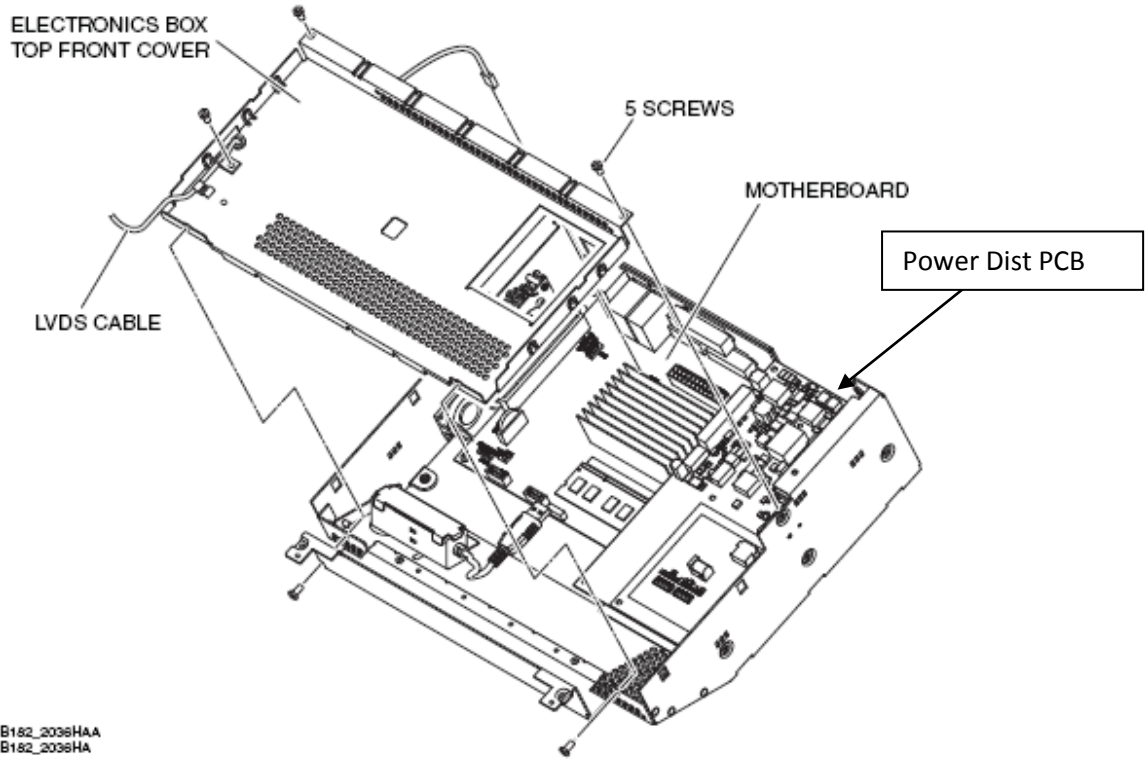
- 11 SCREWS
- ELECTRONICS BOX BACK COVER

[2] Disconnect the MODEM CABLE (SCAN STATION 720EX only).

[3] Remove:

- 2 SCREWS
- ELECTRONICS BOX TOP BACK COVER

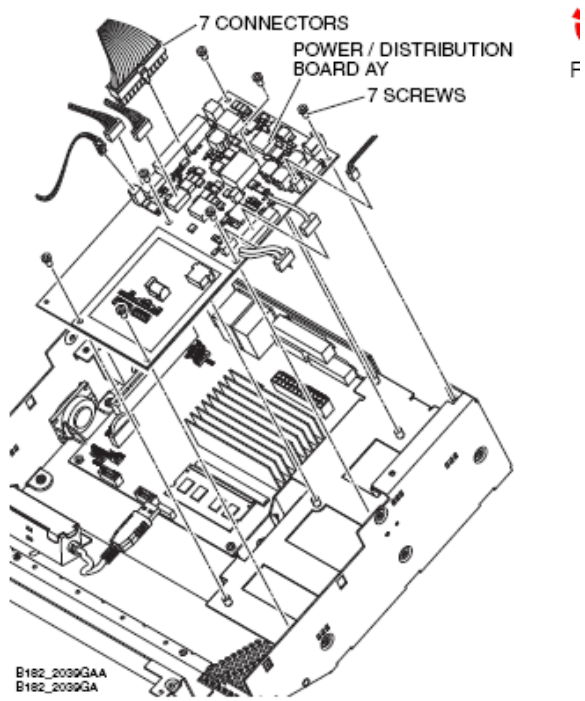


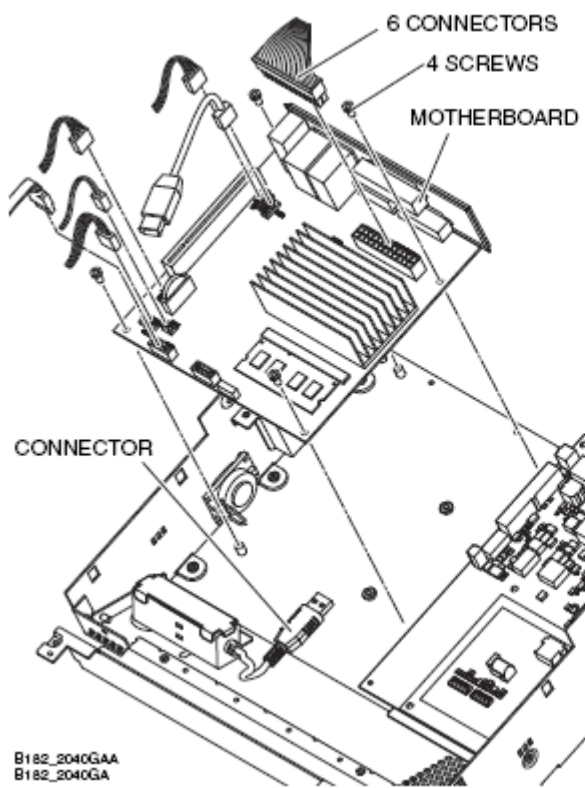


[4] Remove:

- 5 SCREWS
- ELECTRONICS BOX TOP FRONT COVER

[5] Disconnect the LVDS CABLE from the MOTHERBOARD.

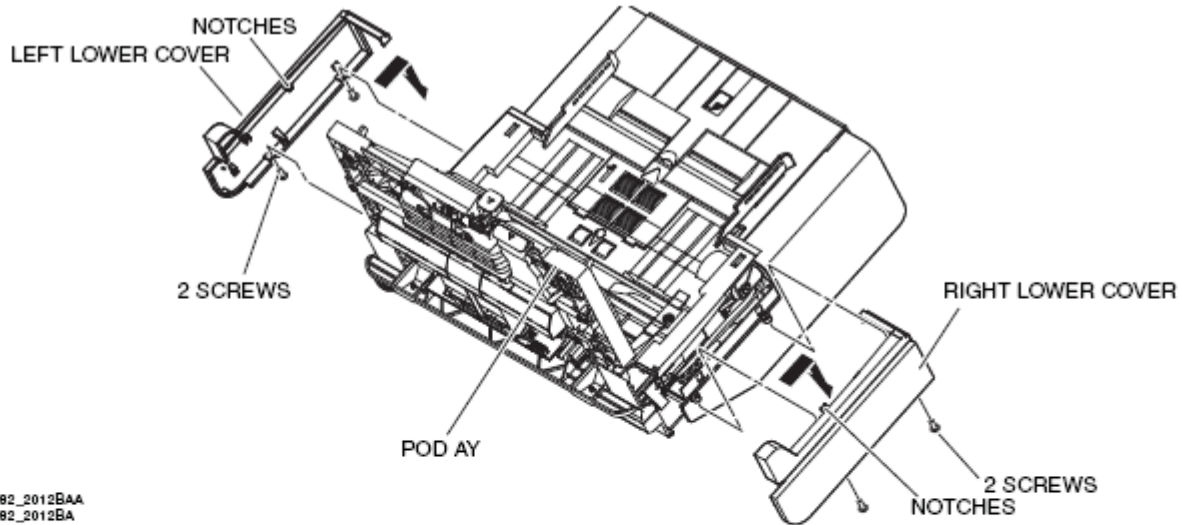




- [1] Disconnect:
- 6 CONNECTORS
 - CONNECTOR (SCAN STATION 720EX only)
- [2] Remove:
- 4 SCREWS
 - MOTHERBOARD

Scan Module Control Printed Circuit Board removal

Remove right and left lower covers



B192_2012BAA
B192_2012BA

[1] Open the POD AY.



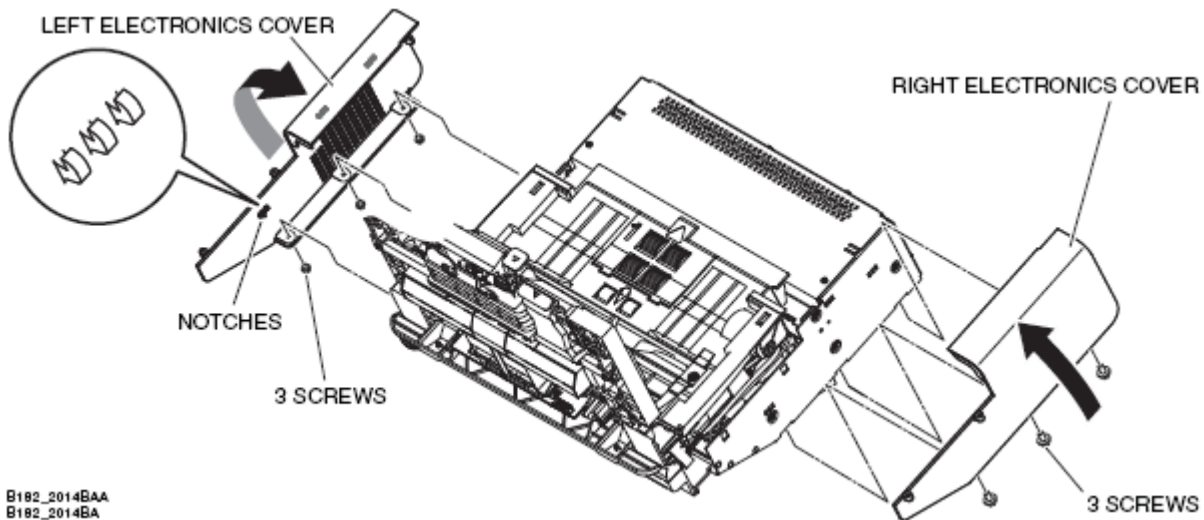
Caution

Prevent damage to the NOTCHES inside the COVERS by moving each COVER toward the back and down.

[2] Remove:

- 2 T-10 SCREWS
- RIGHT LOWER COVER
- 2 T-10 SCREWS
- LEFT LOWER COVER

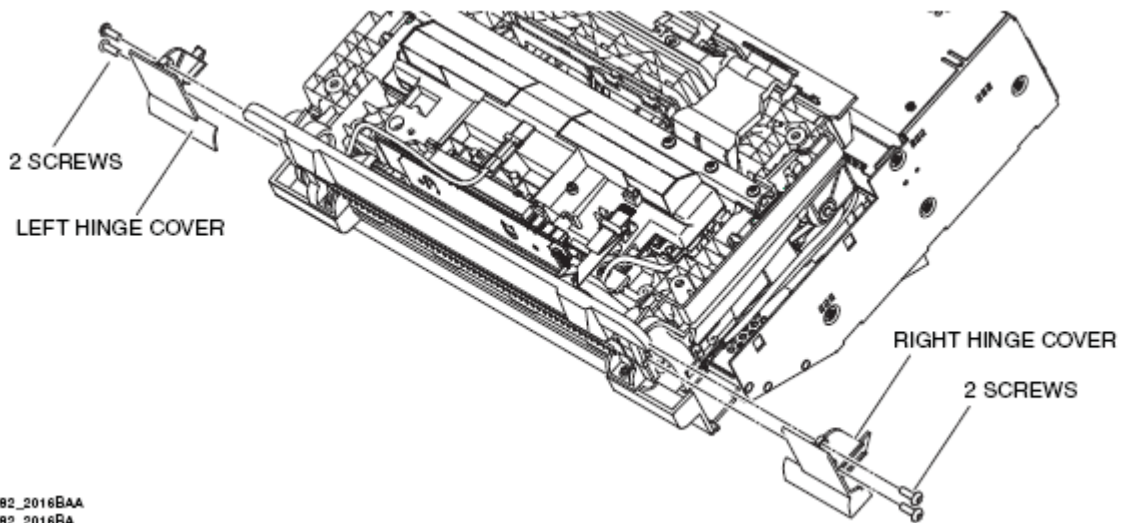
Remove right and left electronic covers



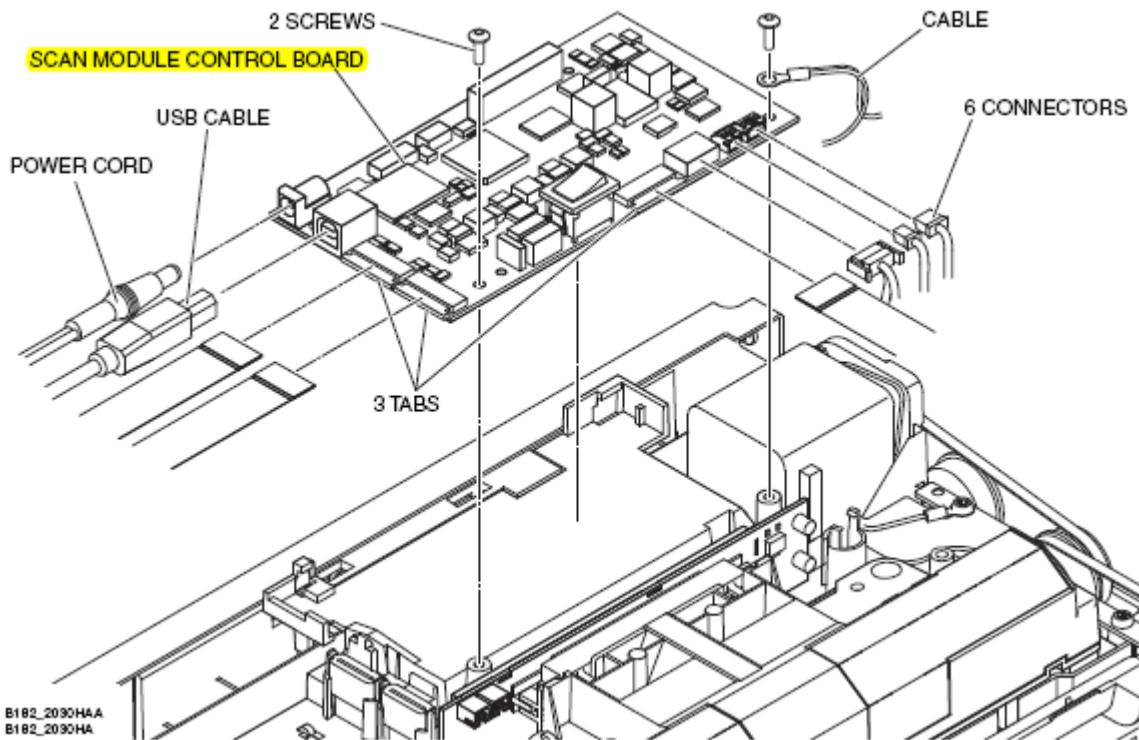
B192_2014BAA
B192_2014BA

[1] Remove:

- 3 T-10 SCREWS
- RIGHT ELECTRONICS COVER
- 3 T-10 SCREWS
- LEFT ELECTRONICS COVER



B182_2016BAA
B182_2016BA



B182_2030HAA
B182_2030HA

EOL Strategy

The product EOL strategy will be based on market needs, regulations, financial impact, etc. For example, the WEEE Directive in the European Union requires that a collection and treatment infrastructure is in place to manage our products at end-of-life. This obligation will be met through membership in a variety of governmental and industry-led collection schemes, as well as Kodak Alaris initiated strategies developed specifically for Kodak Alaris products. Strategies such as re-use, re-conditioning, strip and salvage, responsible disposal, etc. can vary by region and change with time.

Regulatory Requirements

The hazardous materials that are contained within this product need to be handled in compliance with the local requirements when discarded by the final user and sent for end-of-life treatment.

For recycler processes; substances, preparations, and components may be removed manually, mechanically, or chemically, metallurgically with the result that hazardous substances, preparation, components are contained in an identifiable waste stream or identifiable part of a waste stream at the end of the treatment process.

- LCDs (liquid crystal displays) must be processed by vendors capable of and experienced in recovering mercury in backlights.
- Lithium Ion batteries – prior to the smelting process, plastics are separated from the metal components. The metals are then recycled via High Temperature Metal Reclamation (HTMR) process during which all of the high temperature metals contained within the battery feedstock (ie nickel, iron, manganese, and chromium) report to the molten-metal bath within the furnace, amalgamate, then solidify during the casting operation. The low temperature metals (ie, zinc and cadmium) separate during the melting. These batteries are 100% recyclable.
- PC (printed circuit) boards must be processed by a smelter (or other thermal process) capable of and experienced in recovering precious metals (gold and so forth) and heavy metals (lead and so forth) for reuse or by a chemical recovery process. Circuit components may be extracted for reuse prior to smelting.
- Plastics should be recycled for use in new products, components and materials, as substitutes for other raw materials, or recycled in another beneficial manner. When recycling is not economically practical, plastics should be processed for energy recovery at a facility that is designed to control and monitor emissions from the process. See section 14.9 for related information.
- Metal (other than in PC boards): Acceptable processing includes liberation of metal items (manually or mechanically), volume reduction for transport (shredding, baling, and so forth), and refining by smelters or foundries (or similar) for the purpose of preparing the metal for reuse. To maximize recycling rates, sending whole products to a smelter is not authorized without approval from HP and demonstration that the smelter is capable of capturing all of the following for reuse: copper, precious metals (such as gold and silver); steel and aluminum; and, for CRT devices, lead.
- Incineration: If lead-bearing electronic components (such as circuit boards), batteries, polyvinyl chloride (PVC) plastics, mercury lamps, or any material classified as hazardous waste under applicable regulations are disposed of by incineration, the incinerator must meet 99.99% destruction removal efficiency (DRE) for all regulated hazardous contaminants and 99.9999% DRE for dioxins.

The following regulations/directives apply to these products.

WEEE

Equipment Labeling Plans

As per WEEE requirements the equipment is labeled with the dustbin symbol.

Information for Customers and Treatment Facilities

When the last user wishes to discard this product, the information that will guide the customer's action will be available on-line. The disposal information will be made available to the recycler through instructions via Kodak Alaris website.

Information provided to the user in the User Manual includes the meaning of the dustbin symbol, instructions not to dispose as unsorted municipal waste, available collection system and their role in contributing to WEEE goals and potential environmental and health effects as a result of the presence of hazardous substances.